

PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company		STMicroelectronics International N.V
1.2 PCN No.	ADG/18/10865	
1.3 Title of PCN	RDL and bumping transfer from the current subco in Taiwan to a new one in Taiwan	
1.4 Product Category	Chipbond in Taiwxan	
1.5 Issue date	2018-04-24	

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Richard RENARD
2.1.2 Marketing Manager	Eric PARIS
2.1.3 Quality Manager	Jean-Paul REBRASSE

3. Change

3.1 Category	3.2 Type of change	3.3 Manufacturing Location
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Wafer fabrication	ASE subco in China

4. Description of change

	Old	New
4.1 Description	RDL and bumping at subco in Taiwan	RDL and bumping at a new subco in Taiwan (transfer)
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	no	

5. Reason / motivation for change

5.1 Motivation	The current 6 inches RDL and bumping line will be terminated in December 2018.
5.2 Customer Benefit	MANUFACTURING FLEXIBILITY

6. Marking of parts / traceability of change

6.1 Description	internal codification, new marking and QA number
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7. Timing / schedule

7.1 Date of qualification results	2018-04-24
7.2 Intended start of delivery	2018-08-13
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	Issue Date	

9. Attachments (additional documentations)

10865 Public product.pdf
10865 PCN qualif EMIF06-HSD03F3_ Taiwan.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	EMIF06-HSD03F3	

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Public Products List

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PCN Title : RDL and bumping transfer from the current subco in Taiwan to a new one in Taiwan

PCN Reference : ADG/18/10865

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

EMIF06-HSD03F3		
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